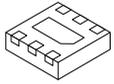


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

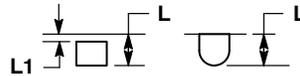
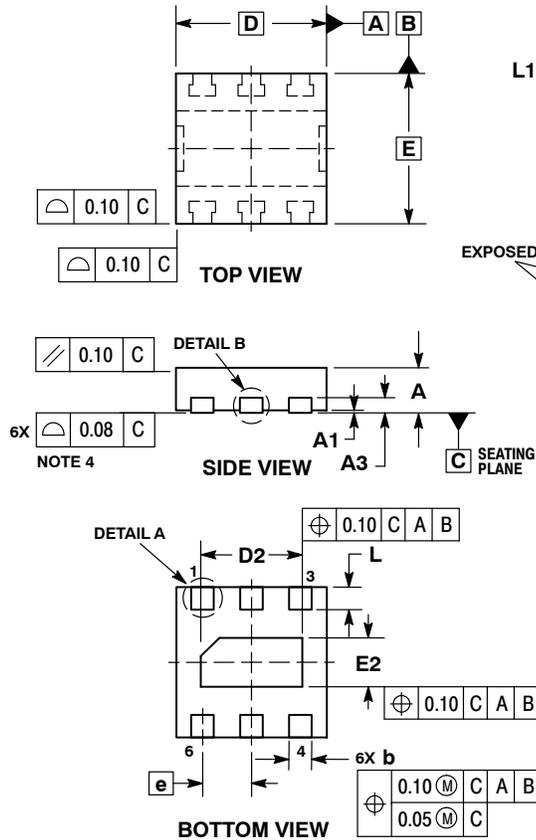
ON Semiconductor®



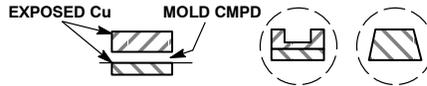
SCALE 4:1

CUDFN6 2x2, 0.65P
CASE 505AK
ISSUE O

DATE 08 JAN 2014



DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS



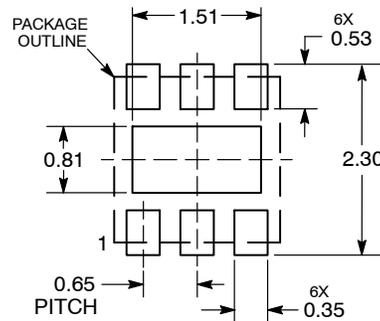
DETAIL B
ALTERNATE CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. TIE BARS MAY BE VISIBLE IN THIS VIEW AND ARE CONNECTED TO THE THERMAL PAD.

DIM	MILLIMETERS	
	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
A3	0.203 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.25	1.45
E	2.00 BSC	
E2	0.55	0.75
e	0.65 BSC	
L	0.25	0.35
L1	---	0.15

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	CUDFN6 2X2, 0.65P	PAGE 1 OF 2

